EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE

ABSTRACT

It is an object of the present invention to provide an epoxy resin composition for semiconductor encapsulation which has good solder heat resistance and excellent productivity, and a semiconductor device. The invention solves the problems by means of an epoxy resin composition for semiconductor encapsulation comprising (A) an epoxy resin, (B) a phenolic resin, (C) (C-1) an organopolysiloxane having a carboxyl group and/or (C-2) a reaction product between an organopolysiloxane having a carboxyl group and an epoxy resin, and (D) a tri-fatty acid ester of glycerol.

Figure 1